ON Semiconductor®

Final Product/Process Change Notification

Document #:FPCN22647XBE
Issue Date:11 Aug 2021

Title of Change:	Mold Compound Change attributed to an End of Life of Samsung SDI EMC for TO247 in SHEDCL
Proposed First Ship date:	22 Nov 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Bokyun.Seo@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Lalan.Ortega@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	No change of Marking of Parts / Traceability of Change
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Suzhou, China	SHANTOU HUASHAN Electronic Devices Co., Ltd., China

Description and Purpose:

ON Semiconductor wishes to inform a change in mold compounds used for the devices listed in this PCN. This is the final product change notification (FPCN). This change is a result of an End of Life notification received from Samsung for several of their SDI Mold Compounds. Due to the discontinuance of the SDI mold compounds, ON Semiconductor will only have limited supplies of the existing material.

	Before Change Description	**After Change Description**
Mold compound	SL7300HFM, Supplier: Samsung SDI	EME6600CS S4L, Supplier : SUMITOMO

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME: HGTG27N120BN
RMS: U60275, O62995, 77932
PACKAGE: TO247

Test	Specification	Condition	Interval	Result
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0 / 231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0 / 231
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0 / 231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 5.0 min	6000 Cyc	0 / 231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0 / 231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0 / 231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0 / 231
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90
SD	JSTD002	Ta = 245C, 5 sec		0/45
PD	JESD22-B100B	Per POD, case outline		0/30
SAT	J-STD-035	Delamination	0hr	0 / 25

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
HGTG5N120BND	HGTG27N120BN
HGTG10N120BND	HGTG27N120BN
FGH30N60LSDTU	HGTG27N120BN